

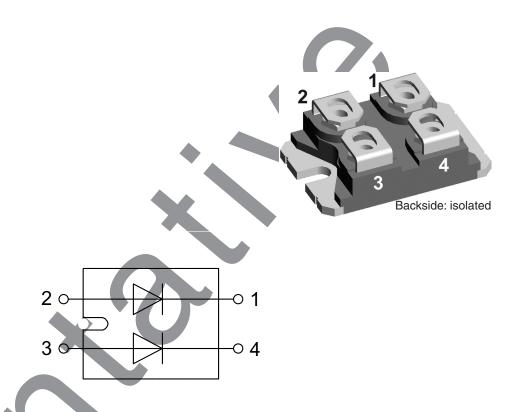
1200 V V_{RRM}

 $= 2 \times 64 A$ I_{FΔV}

SiC Schottky Diode

Ultra fast switching Zero reverse recovery

Part number DCG130X1200NA



Features / Advantages:

- · Ultra fast switching
- · Zero reverse recovery
- Zero forward recovery
- Temperature independent switching behavior
- Positive temperature coefficient of forward voltage
- $\bullet T_{VJM} = 175^{\circ}C$

Applications:

- Solar inverter
- Uninterruptible power supply (UPS)
- Welding equipment
- Switched-mode power supplies
- Medical equipment
- · High speed rectifier

Package: SOT-227B (minibloc)

- Isolation Voltage: 3000 V~
- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0
- Base plate with Aluminium nitride isolation for low thermal resistance
- Advanced power cycling

Terms & Conditions of Usage

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you. Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you. Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

- to perform joint risk and quality assessments;
- the conclusion of quality agreements;
 to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, test conditions and dimensions.

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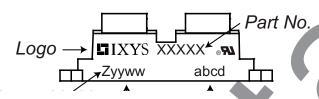
SiC Diode					Ratings		
Symbol	Definitions	Conditions	min.	typ.	max.		
V _{RSM}	max. non-repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
V _{RRM}	max. repetitive reverse blocking voltage	$T_{VJ} = 25^{\circ}C$			1200	V	
I _R	reverse current	$V_{\text{R}} = V_{\text{RRM}} \qquad \qquad T_{\text{VJ}} = 25^{\circ}\text{C} \\ T_{\text{VJ}} = 175^{\circ}\text{C}$		140 480	800 1200	μ Α μ Α	
V _F	forward voltage	$I_F = 30 \text{ A}$ $T_{VJ} = 25^{\circ}\text{C}$ $I_F = 60 \text{ A}$		1.3 1.6	1.8	V V	
		$I_F = 30 \text{ A}$ $T_{VJ} = 175^{\circ}\text{C}$ $I_F = 60 \text{ A}$		1.55 2.3	3	V V	
I _{FAV}	average forward current	$T_{c} = 80^{\circ}C$ rectangular, d = 0.5 $T_{c} = 100^{\circ}C$ $T_{v,j} = 175^{\circ}C$			64 57	A A	
_{F25} _{F80} _{F100}	forward current	$T_{\rm C} = 25^{\circ}{\rm C}$ $T_{\rm C} = 80^{\circ}{\rm C}$ $T_{\rm C} = 100^{\circ}{\rm C}$			112 88 76	A A A	
I _{FSM}	max forward surge current	$t=10$ ms,half sine (50 Hz) $T_{VJ}=25^{\circ}C$ $V_{R}=10$ μ s, pulse $V_{R}=0$			300 1150	A A	
Q _c	total capacitive charge	$V_R = 800 \text{ V}, I_F = 60 \text{A}$ $T_{VJ} = 25^{\circ}\text{C}$ $dI/dt = 800 \text{ A}/\mu\text{s}$		384		nC	
С	total capacitance	$V_R = 0 V$ $V_R = 400 V$ $V_R = 800 V$ $V_R = 800 V$ $V_R = 800 V$		4800 280 200		pF pF pF	
R_{thJC} R_{thJH}	thermal resistance junction to case thermal resistance junction to heatsink	with heatsink compound; IXYS test setup		0.54	0.39	K/W K/W	





Package	Outlines SOT-227B (minibloc)				Ratings		
Symbol	Definitions	Conditions		mir	. typ.	max.	Unit
I _{RMS}	RMS current	per terminal				100	Α
T _{stg}	storage temperature operation temperature			-4 -4		150 150	 ⊙°
T _{op} T _{VJ}	virtual junction temperature			-4		175	°C
Weight					30		g
M _D	mounting torque 1)	screws to heats				1.5 1.3	Nm Nm
d _{Spp}	creepage distance on surface		terminal to terminal terminal to backside	10.			mm mm
d _{App}	striking distance through air		terminal to terminal terminal to backside	3.: 6.			mm mm
V _{ISOL}	isolation voltage	t = 1 second t = 1 minute	50 / 60 Hz, RMS; I _{ISOL} ≤ 1	nA 300	1 = -		V
C _P	coupling capacity per switch	between shorted to metallization	erminals of diodes and back side				pF
¹) further information see application note IXAN0073 on www.ixys.com/TechnicalSupport/appnotes.aspx (General / Isolation, Mounting, Soldering, Cooling)							

Product Marking



Part description

D = Diode
C = SiC
G = Extreme fast
130 = Current Rating [A]
X = Parallel legs
1200 = Reverse Voltage [V]
NA = SOT-227 (minibloc)

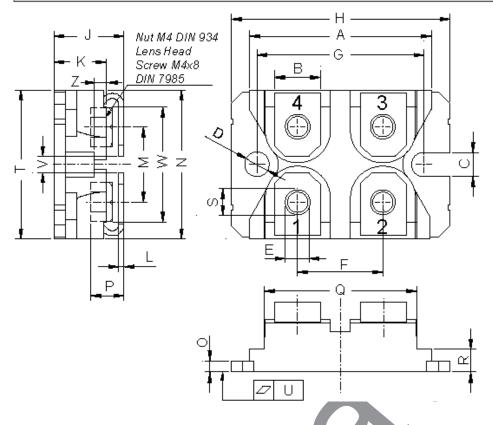
Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	DCG130X1200NA	DCG130X1200NA	Tube	10	521458

Equivalent Circuits for Simulation *on die level						
$I \rightarrow V_0$	$T_{VJ} = 125$ °C	T _{VJ} = 175°C				
V_{0max}	threshold voltage	0.60	V			
R_{0max}	slope resistance *	24.9	mΩ			





Outlines SOT-227B (minibloc)



Dim.	Millimeter		Inches		
DIIII.	min	max	min	max	
Α	31.50	31.88	1.240	1.255	
В	7.80	8.20	0.307	0.323	
С	4.09	4.29	0.161	0.169	
D	4.09	4.29	0.161	0.169	
Е	4.09	4.29	0.161	0.169	
F	14.91	15.11	0.587	0.595	
G	30.12	30.30	1.186	1.193	
Н	37.80	38.23	1.488	1.505	
J	11.68	12.22	0.460	0.481	
K	8.92	9.60	0.351	0.378	
L	0.74	0.84	0.029	0.033	
M	12.50	13.10	0.492	0.516	
N	25.15	25.42	0.990	1.001	
0	1.95	2.13	0.077	0.084	
Р	4.95	6.20	0.195	0.244	
Q	26.54	26.90	1.045	1.059	
R	3.94	4.42	0.155	0.167	
S	4.55	4.85	0.179	0.191	
Τ	24.59	25.25	0.968	0.994	
U	-0.05	0.10	-0.002	0.004	
V	3.20	5.50	0.126	0.217	
W	19.81	21.08	0.780	0.830	
Ζ	2.50	2.70	0.098	0.106	

